


Standardized Information for Process/Product Change Notification (PCN)

| 1. PCN basic data | | |
|-------------------------------------|--|---|
| 1.1 Company |  | TAIWAN SEMICONDUCTOR CO.,LTD |
| 1.2 PCN No. | PCN21007 | |
| 1.3 Title of PCN | SMD Products Change of Encapsulation Material, Packing Material and Datasheet Revision | |
| 1.4 Product Category | Active Components - Discrete Components | |
| 1.5 Issue date | 2021/05/12 | |
| 1.6 PCN revision history (optional) | 1.7 Issue date of previous revision (optional) | 1.8 Delta to previous revision (optional) |
| | | |
| | | |


Form provided by ZVEI - Revision 4.0

| 2. PCN Team | | |
|------------------------------|---------------------------|-----------------------------|
| 2.1 Contact supplier | | |
| 2.1.1 Name | Sunnie Lin | |
| 2.1.2 Phone | +886-2-8913-1588 Ext:2205 | |
| 2.1.3 Email | sunnie.lin@mail.ts.com.tw | |
| 2.2 Team supplier (optional) | | |
| 2.2.1 Name (optional) | 2.2.2 Phone (optional) | 2.2.3 Email (optional) |
| Vince Lee | +86 5438691091 ext. 3101 | vince.lee@mail.tsyew.com.cn |
| Danny Lin | +886-2-8913-1588 Ext:2133 | danny.lin@mail.ts.com.tw |
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| 3. Changes | | | |
|------------|-----------|--------------------|--|
| No. | 3.0 Ident | 3.1 Category | 3.2 Type of change |
| #1 | SEM-DS-02 | DATA SHEET | Correction of data sheet / errata |
| #2 | SEM-PA-11 | PROCESS - ASSEMBLY | Change of mold compound / encapsulation material |
| #3 | SEM-PS-01 | PACKING/SHIPPING | Packing/shipping specification change |

| 4. Description of change | | |
|---|--|--|
| | Old | New |
| Change #1 | <ul style="list-style-type: none"> Ordering Information (with Packing Code) None | <ul style="list-style-type: none"> Ordering Information (Without Packing Code) Add note: Meets ISO 7637-2 (Pulse 1/2a/3a/3b) (TVS Products Only) |
| Change #2 | <ul style="list-style-type: none"> Non Green Compound and Green Cpmound | <ul style="list-style-type: none"> Green Compound |
| Change #3 | <ul style="list-style-type: none"> 13/7 inch Plastic & Paper Reel & Tube Sub SMA : 8/12 mm tape width different number of pieces on reel (1800, 3000, 7500, 10000) | <ul style="list-style-type: none"> 13 inch Plastic Reel Sub SMA : 8mm tape width 10000 pieces |
| 4.1 Anticipated impact on form, fit, function, reliability or processability? | Not impact the form, fit, function, reliability or processability. | |
| 4.2 Reference parts with customer number (optional) | | |

| 5. Reason / motivation for change | |
|--|---|
| 5.1 Motivation | Taiwan Semiconductor will implement halogen-free (green) epoxy molding for all SMD devices to be compliant to global environmental initiatives in line with IEC 61249-2-21. Accordingly, the packing material will be standardized to 13 inch plastic reel. In line with this change, the product datasheets will also be revised to simplify the ordering code. TVS Products manufactured in SOD-123W, SOD-128 and Thin SMA packages will have a note in datasheet describing the compliance to ISO 7637-2 |
| 5.2 Additional explanation (optional) | |

| 6. Marking of parts / traceability of change | |
|--|---|
| 6.1 Description | Product date code to traceability  |

| 7. Timing / schedule | | |
|---|--|---|
| 7.1 Date of qualification results | | Qualification date are based on different product package |
| 7.2 Last order date (optional) | 2022/12/31 | with packing code parts |
| 7.3 Last delivery date (optional) | 2023/06/30 | with packing code parts |
| 7.4 Intended start of delivery | 2021/10/01 | without packing code parts |
| 7.5 Qualification samples available? | When get customer order and after 2 weeks can be submitted | |
| 7.6 Customer feedback required until | 2021/06/26 | |

| 8. Qualification / validation | | | |
|---|----------------------------|------------|--|
| 8.1 Description (e.g. qual. plan/report, AEC-Q...) | According to AEC-Q101 | | |
| 8.2 Qualification report and qualification results | available (see attachment) | issue date | |

| 9. Input to customer for risk assessment process |
|---|
| There is no impact in product specification, functionality, quality, reliability. Implementing the change to green compound will guarantee Taiwan Semiconductor commitment on environmental protection. |

| 10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...) |
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| Refer to the official e-mail announcement for the applicable documents. |

| 11. Affected parts | | | | | | | | | |
|--------------------------|---------------------------|-------------------------------------|---------------------|------------------------------------|---|---------------------------|-------------------------------------|---------------------|---|
| 11.1 Current | | | | | | 11.2 New (if applicable) | | | |
| 11.1.1 Customer Part No. | 11.1.2 Supplier Part Name | 11.1.3 Supplier Part No. (optional) | 11.1.4 Package Name | 11.1.5 Part Description (optional) | 11.1.6 Additional Part Information (optional) | 11.2.2 Supplier Part Name | 11.2.3 Supplier Part No. (optional) | 11.2.4 Package Name | 11.2.6 Additional Part Information (optional) |
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